

**IN THE CLAIMS**

Please amend the claims as follows:

Claim 1 (currently amended): A multi-layer printed wiring board comprising:

a first substrate having an opening and having a plurality of external terminals positioned to be connected to a package substrate;

a second substrate laminated to the first substrate and having a plurality of external terminals positioned to be connected to a mother board, the second substrate having a metallic layer portion in the opening of the first substrate and a plurality of non-through holes filled with conductive material and connected to the metallic layer portion; and

an IC component having a plurality of terminals and loaded in the opening of the first substrate such that the terminals of the IC component face an opposite side of the metallic layer portion of the second substrate,

wherein the IC chip is accommodated in the opening such that the metallic layer portion and non-through holes of the second substrate irradiate heat generated by the IC chip.

Claim 2 (canceled)

Claim 3 (previously presented): The multi-layer printed wiring board according to claim 1, wherein the external terminals of the first substrate are disposed offset the external terminals of the second substrate.

Claim 4 (previously presented): The multi-layer printed wiring board according to claim 1, further comprising a plurality of conductive non-through holes provided in the first substrate and connected to the external terminals of the first substrate and a plurality of conductive non-through holes provided in the second substrate and connected to the external terminals of the second substrate, wherein the conductive non-through holes in the first substrate and the conductive non-through holes in the second substrate are positioned offset from each other.

Claim 5 (canceled)

Claim 6 (previously presented): The multi-layer printed wiring board according to claim 4, wherein the conductive non-through holes in the first and second substrates are provided with a plurality of conductive bumps, respectively.

Claim 7 (previously presented): The multi-layer printed wiring board according to claims 1, further comprising a plurality of bonding pads provided for wire bonding the IC component in the first substrate.

Claim 8 (previously presented): The multi-layer printed wiring board according to claim 7, wherein the plurality of bonding pads are connected to a plurality of conductive non-through holes formed underneath the plurality of bonding pads, respectively.

Claims 9-10 (canceled)

Claim 11 (previously presented): The multi-layer printed wiring board according to claim 7, wherein the bonding pads have a rectangular shape.

Claim 12 (previously presented): The multi-layer printed wiring board according to claim 8, wherein the plurality of conductive non-through holes formed underneath the plurality of bonding pads, respectively, has a plurality of conductive bumps, respectively, on an opposite face of the bonding pads.

Claims 13-17 (canceled)

Claim 18 (new): The multi-layer printed wiring board according to claim 1, wherein the external terminals of the first substrate are positioned in a peripheral form surrounding the IC component, and the external terminals of the second substrate are positioned in a grid form.